FOR IMMEDIATE RELEASE

Contacts:
Aehr Test Systems
Carl Buck
V.P. of Marketing
(510) 623-9400 x381
cbuck@aehr.com

MKR Group Inc.
Todd Kehrli or Jim Byers
Analyst/Investor Contact
(323) 468-2300
aehr@mkr-group.com

Aehr Test Systems Announces Achievement of NAND Flash Testing Milestone on FOX-XP™ Multi-Wafer Test and Burn-in System

Fremont, CA (May 27, 2015) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced the achievement of an important milestone in the development of its next-generation FOX-XP Wafer-Level Test and Burn-in System. The achievement of NAND flash testing is one of a series of NRE funding related milestones associated with the customer evaluation order the Company announced in January from a leading IC manufacturer for the FOX-XP multi-wafer solution.

Working with this leading IC manufacturer, Aehr Test successfully demonstrated test and correlation of a high-density NAND flash memory with its next-generation FOX-P system electronics. The test results showed correlation with the IC manufacturer's current production Automated Test Equipment (ATE) test system, including matching the failing bits within the flash memory.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, "We are very excited to announce this important milestone in the development of our next-generation FOX-P systems. We expect our new FOX-XP system to open up significant opportunities for Aehr Test, particularly in the rapidly growing NAND SSD market. We believe that wafer-level burn-in and test is a key enabler for producing reliable multi-die stacked NAND packages for enterprise Solid State Drives (SSDs) and other high-reliability and stacked-die applications in a cost effective way."

Aehr Test is developing the FOX-XP system, its next-generation multi-wafer test solution that is capable of functional test and burn-in/cycling of flash memories, microcontrollers and other leading-edge ICs in wafer form before they are assembled into multi-die stacked packages. These stacked packages can then be used for high reliability and quality applications such as enterprise solid state drives, automotive devices, mission critical integrated circuits and sensors.

The FOX-XP system utilizes Aehr Test's FOX WaferPak contactors, which are designed to provide a cost effective solution for making electrical contact with a full wafer or substrate in a multi-wafer environment. Aehr Test's WaferPak contactors contain up to tens of thousands of probes to contact all devices simultaneously on wafers and substrates up to 300mm in diameter. The FOX-XP system is being developed in configurations with up to 25 wafers in parallel in a single system to operate within an efficient manufacturing space footprint.

Aehr Test estimates the test equipment and consumables for this emerging market will add $200 million to $300 million to its served available market annually.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligner and WaferPak contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

###